QPTECHNOLOGIES

JOB DESCRIPTION - EXEMPT

Position Title:	Micro Assembly Engineer			**Position # or Level :**	
Department:	Engineering		**Reports to:**	TBD	
Employment Status:	(Indicate if position is full time or part time)	**Pay Grade or salary range:**	(List the pay grade or salary range for this position)	**% Travel Required**	(List % of travel for this position)

Position Summary:

The Micro Assembly Engineer is primarily responsible for wire bonding, along with supporting Die Attach, Encapsulation, and Laser Marking processes. This role programs and operates automated wire bond and semiconductor packaging equipment, troubleshoots process and equipment issues, and partners with Process Engineering, Quality, and Production to maintain performance to specification. The Micro Assembly Engineer drives improvements in yield, process capability, and reliability while supporting new product introductions and production operations in QP Technology's high-mix facility.

Essential Duties: Other Duties & Responsibilities

- Program, set up, and run wire bonding equipment as the primary process owner, with additional responsibility for die attach, flip-chip, encapsulation, and other machine-driven assembly operations.
- Perform process characterization, DOE, SPC analysis, and root cause investigations to improve yield, reliability, and process capability.
- Define and maintain process parameters, work instructions, specifications, and control plans, including best practices for process setup, control, and changeovers.
- Support new product introduction (NPI) in a high-mix manufacturing environment.
- Collaborate with Quality, Production, and Engineering to resolve process and equipment issues.
- Lead corrective and preventive actions (CAPA) for process-related issues and ensure compliance with customer, industry, and internal quality standards.
- Train technicians and operators on wire bonding and other assembly processes.

Minimum Qualifications:

- Bachelor's degree in electrical engineering, Mechanical Engineering, Materials Science, Semiconductor Engineering, or related field, or commensurate industrial experience.
- 5+ years of experience in electronic assembly, semiconductor packaging, or microelectronics manufacturing.
- Hands-on experience with automatic wire bonders (gold, copper, aluminum ball, wedge, and ribbon bonding).
- Knowledge of wire bonding physical principles, semiconductor assembly and package technologies.
- Experience with statistical tools such as SPC, DOE, and FMEA.

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- Excellent communication and teamwork abilities.

Key Competencies:

- Wire Bonding & Semiconductor Packaging
- Assembly Process Development & Continuous Improvement
- Failure Analysis & Root Cause Analysis
- Yield Improvement
- SPC & Process Control
- Strong Problem-Solving & Data Analysis
- Attention to Detail & Process Discipline

Preferred Skills:

- Experience with advanced packaging technologies, including BGA, QFN, SIP, and Flip Chip.
- Familiarity with SEM, failure analysis techniques, and reliability testing.
- Knowledge of Lean Manufacturing and Six Sigma methodologies, with Green Belt or Six Sigma certification preferred.

Work Environment: While performing the duties of the job, the employee is regularly required to sit, stand and/or walk for extended periods of time; use hands and fingers; reach with hands and arms; and talk and hear.
Ability to lift 30 pounds
Observe ESD and safety practices
Wear cleanroom attire on occasion
Must be a U. S. Citizen or Permanent Resident

Employee Acknowledgement:

I have read this job description, and I fully understand all my job duties and responsibilities.

Print Name	Signature	Date	

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